

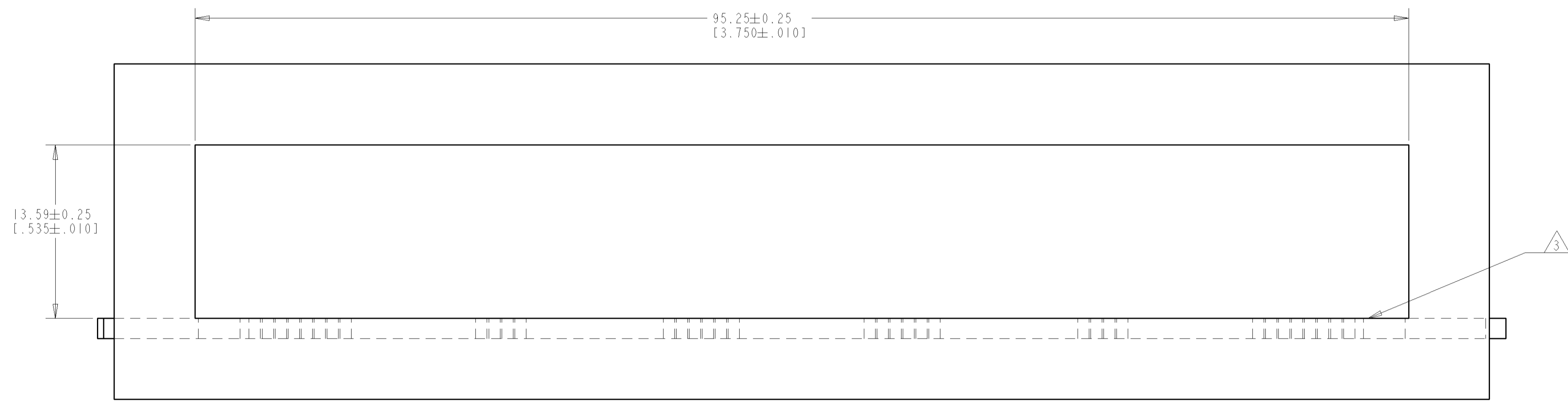
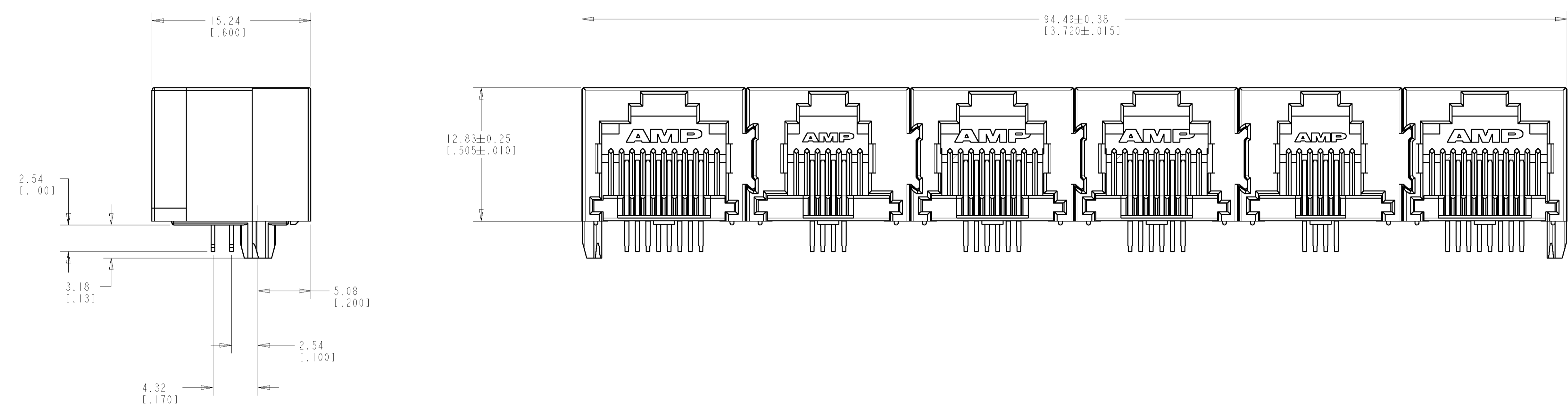


LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DNW	APVD
A		RELEASED	28DEC2005	RG	JW
B		ECO-06-002848	13FEB2006	LAM	JW

- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC,  
 BLACK, UL94V-0  
 TERMINALS - 0.361.0141 THK. PHOS. BRONZE  
 PLATED WITH 3.81um [.000150] MIN. THK. MATTE TIN IN SOLDER  
 AREA. 1.27um [.000050] MIN GOLD IN LOCALIZED PLATE AREA. ENTIRE  
 TERMINAL PLATED WITH 1.27um [.000050] MIN. THK. NICKEL
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART  
 68, SUBPART F

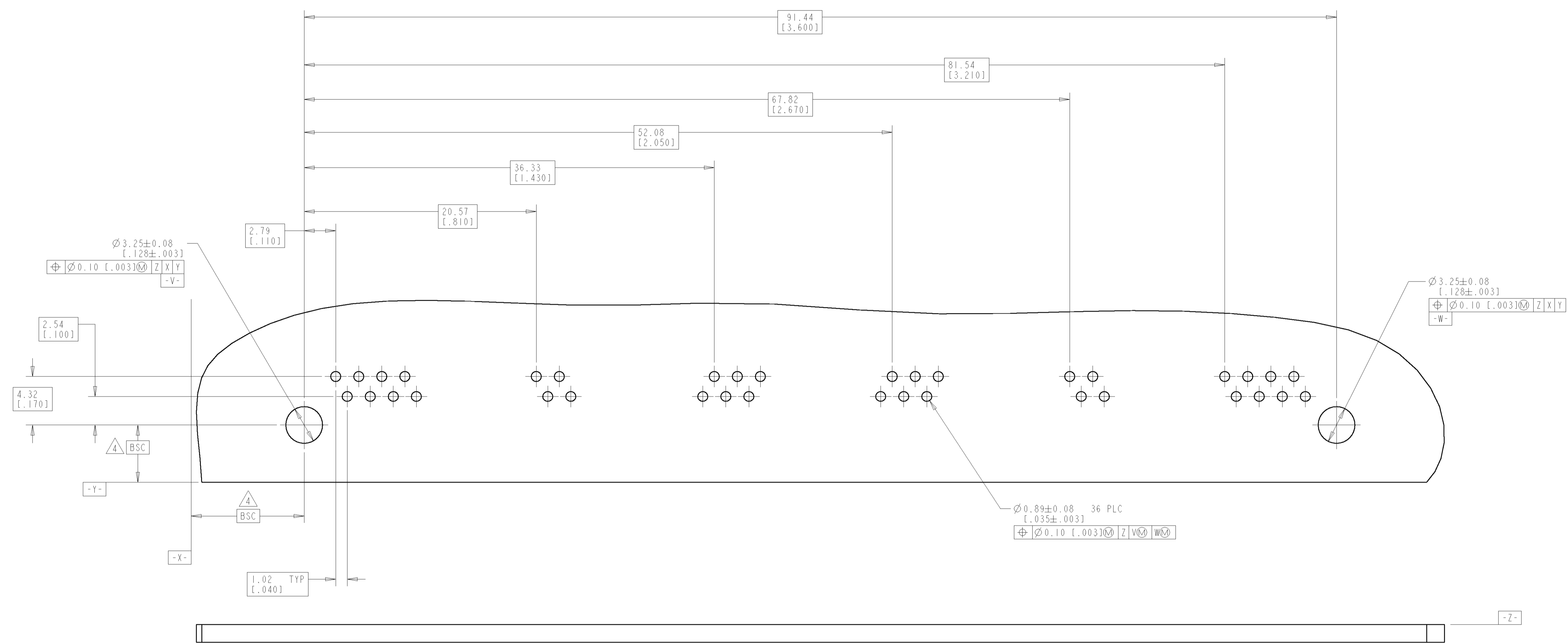
-  PC BOARD IS EVEN WITH PANEL CUTOUT
-  DIMENSION TO BE DETERMINED BY CUSTOMER



**SUGGESTED PANEL OPENING**  
 SCALE 4:1

8P + 4P + 6P + 6P + 4P + 8P		1888298-1	
DESCRIPTION		PART NUMBER	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ±	
MATERIAL: SEE NOTE 1		FINISH: SEE NOTE 1	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ±	
MATERIAL: SEE NOTE 1		FINISH: SEE NOTE 1	
DIMENSIONS: mm [INCHES]		TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ±	
MATERIAL: SEE NOTE 1		FINISH: SEE NOTE 1	

LOC	DIST	REVISIONS			
P	LTR	DESCRIPTION	DATE	DNW	APVD
-	-	SEE SHEET 1	-	-	-



SUGGESTED PRINTED CIRCUIT BOARD  
 LAYOUT  
 (COMPONENT SIDE)  
 SCALE 5:1

<small>THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION BY TYCO ELECTRONICS CORPORATION. ALL RIGHTS RESERVED.</small>		DWN: B. GRZYBOWSKI 28DEC2005 ENR: J. WESTMAN 28DEC2005 APVD: S. FLICKINGER 28DEC2005	<b>tyco</b> Electronics Tyco Electronics Harrisburg, PA 17105-3608
DIMENSIONS: mm [ INCHES ]	TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ±	NAME: INVERTED MODULAR JACK ASSEMBLY, 1 X 6 PRODUCT SPEC: APPLICATION SPEC: WEIGHT: - FINISH: SEE NOTE 1	SIZE: A   00779   C=1888298 SCALE: 4:1   SHEET: 2 OF 2   REV: B
MATERIAL: SEE NOTE 1		CUSTOMER DRAWING	